AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Canceled)

2. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 15, wherein the ~~adjusting~~ increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.

3. (Previously Presented) A manufacturing method according to claim 2, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.

4. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 15, wherein the ~~adjusting~~ increasing comprises inserting the microcircuit into a shell having an access on a rear edge.

5. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 15, wherein the ~~adjusting~~ increasing comprises forming an overmolded portion over the microcircuit.

6. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 2, further comprising fastening the microcircuit to the bottom half-shell.

7. (Previously Presented) A manufacturing method according to claim 6, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

8. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 15, wherein the electronic component is disposed at a location offset from a location of the contact pads.

9. (Currently Amended) A manufacturing method according to claim **[[**1**]]** 15, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10 - 14. (Canceled)

15. (Currently Amended) A method for manufacturing a USB electronic key, comprising cutting out, from a tape having a plurality of microcircuits, a portion of the tape including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; ~~said method further comprising~~ and, in a single operation, ~~adjusting~~ increasing the thickness of the cut-out portion of the tape including the one of the microcircuits at least in the area of the contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard.